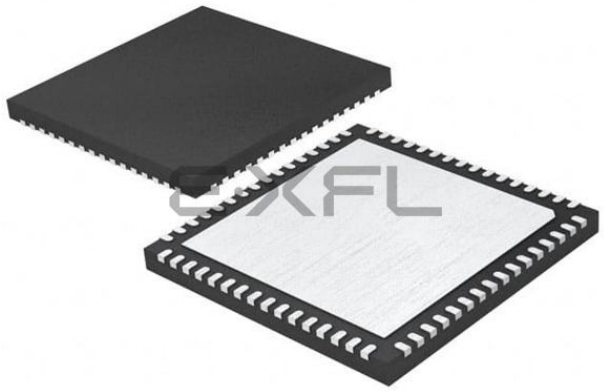

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	-
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	-
Data Converters	A/D 30x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256gm706-h-mr

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com)

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXXGM3XX/6XX/7XX family requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used)
  (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for ADC module is implemented

Note: The AVDD and AVSS pins must be connected independent of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

TABLE 4-22: ADC1 AND ADC2 REGISTER MAP (CONTINUED)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC2BUF9	0352	ADC2 Data Buffer 9																xxxx
ADC2BUFA	0354	ADC2 Data Buffer 10																xxxx
ADC2BUFB	0356	ADC2 Data Buffer 11																xxxx
ADC2BUFC	0358	ADC2 Data Buffer 12																xxxx
ADC2BUFD	035A	ADC2 Data Buffer 13																xxxx
ADC2BUFE	035C	ADC2 Data Buffer 14																xxxx
ADC2BUFF	035E	ADC2 Data Buffer 15																xxxx
AD2CON1	0360	ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM1	FORM0	SSRC2	SSRC1	SSRC0	SSRCG	SIMSAM	ASAM	SAMP	DONE	0000
AD2CON2	0362	VCFG2	VCFG1	VCFG0	OFFCAL	—	CSCNA	CHPS1	CHPS0	BUFS	SMPI4	SMPI3	SMPI2	SMPI1	SMPI0	BUFM	ALTS	0000
AD2CON3	0364	ADRC	—	—	SAMC4	SAMC3	SAMC2	SAMC1	SAMC0	ADCS7	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
AD2CHS123	0366	—	—	—	CH123SB2	CH123SB1	CH123NB1	CH123NB0	CH123SB0	—	—	—	CH123SA2	CH123SA1	CH123NA1	CH123NA0	CH123SA0	0000
AD2CHS0	0368	CH0NB	—	CH0SB5(1)	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0	CH0NA	—	CH0SA5(1)	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0	0000
AD2CSSH	036E	CSS<31:16>																0000
AD2CSSL	0370	CSS<15:0>																0000
AD2CON4	0372	—	—	—	—	—	—	—	ADDMAEN	—	—	—	—	—	DMABL2	DMABL1	DMABL0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Bits 13 and bit 5 are reserved in the AD2CHS0 register, unlike the AD1CHS0 register.

4.5 Modulo Addressing

Modulo Addressing mode is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either Data or Program Space (since the Data Pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into Program Space) and Y Data Spaces. Modulo Addressing can operate on any W Register Pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing since these two registers are used as the Stack Frame Pointer and Stack Pointer, respectively.

In general, any particular circular buffer can be configured to operate in only one direction, as there are certain restrictions on the buffer start address (for incrementing buffers) or end address (for decrementing buffers), based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers that have a power-of-two length. As these buffers satisfy the start and end address criteria, they can operate in a Bidirectional mode (that is, address boundary checks are performed on both the lower and upper address boundaries).

4.5.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and ending address be specified and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 4-1).

Note:	Y space Modulo Addressing EA calculations assume word-sized data (LSb of every EA is always clear).

The length of a circular buffer is not directly specified. It is determined by the difference between the corresponding start and end addresses. The maximum possible length of the circular buffer is 32K words (64 Kbytes).

4.5.2 W ADDRESS REGISTER SELECTION

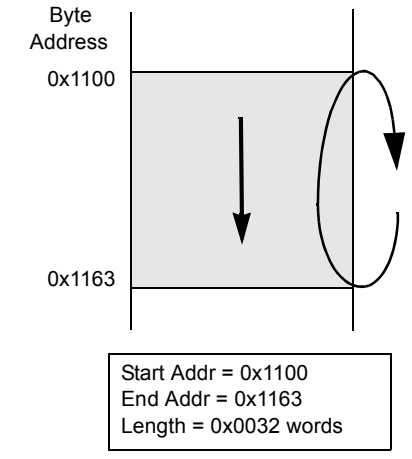
The Modulo and Bit-Reversed Addressing Control register bits, MODCON<15:0>, contain enable flags as well as a W register field to specify the W Address registers. The XWM and YWM fields select the registers that operate with Modulo Addressing:

- If XWM = 1111, X RAGU and X WAGU Modulo Addressing is disabled
- If YWM = 1111, Y AGU Modulo Addressing is disabled

The X Address Space Pointer W register (XWM) to which Modulo Addressing is to be applied is stored in MODCON<3:0> (see Table 4-1). Modulo Addressing is enabled for X Data Space when XWM is set to any value other than '1111' and the XMODEN bit is set (MODCON<15>).

The Y Address Space Pointer W register (YWM) to which Modulo Addressing is to be applied is stored in MODCON<7:4>. Modulo Addressing is enabled for Y Data Space when YWM is set to any value other than '1111' and the YMODEN bit is set (MODCON<14>).

FIGURE 4-14: MODULO ADDRESSING OPERATION EXAMPLE




```
MOV     #0x1100, W0
MOV     W0, XMODSRT     ;set modulo start address
MOV     #0x1163, W0
MOV     W0, MODEND      ;set modulo end address
MOV     #0x8001, W0
MOV     W0, MODCON      ;enable W1, X AGU for modulo

MOV     #0x0000, W0     ;W0 holds buffer fill value

MOV     #0x1110, W1     ;point W1 to buffer

DO      AGAIN, #0x31    ;fill the 50 buffer locations
MOV     W0, [W1++]      ;fill the next location
AGAIN:  INC W0, W0      ;increment the fill value
```

NOTES:

9.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Oscillator"** (DS70580), which is available from the Microchip web site (www.microchip.com).

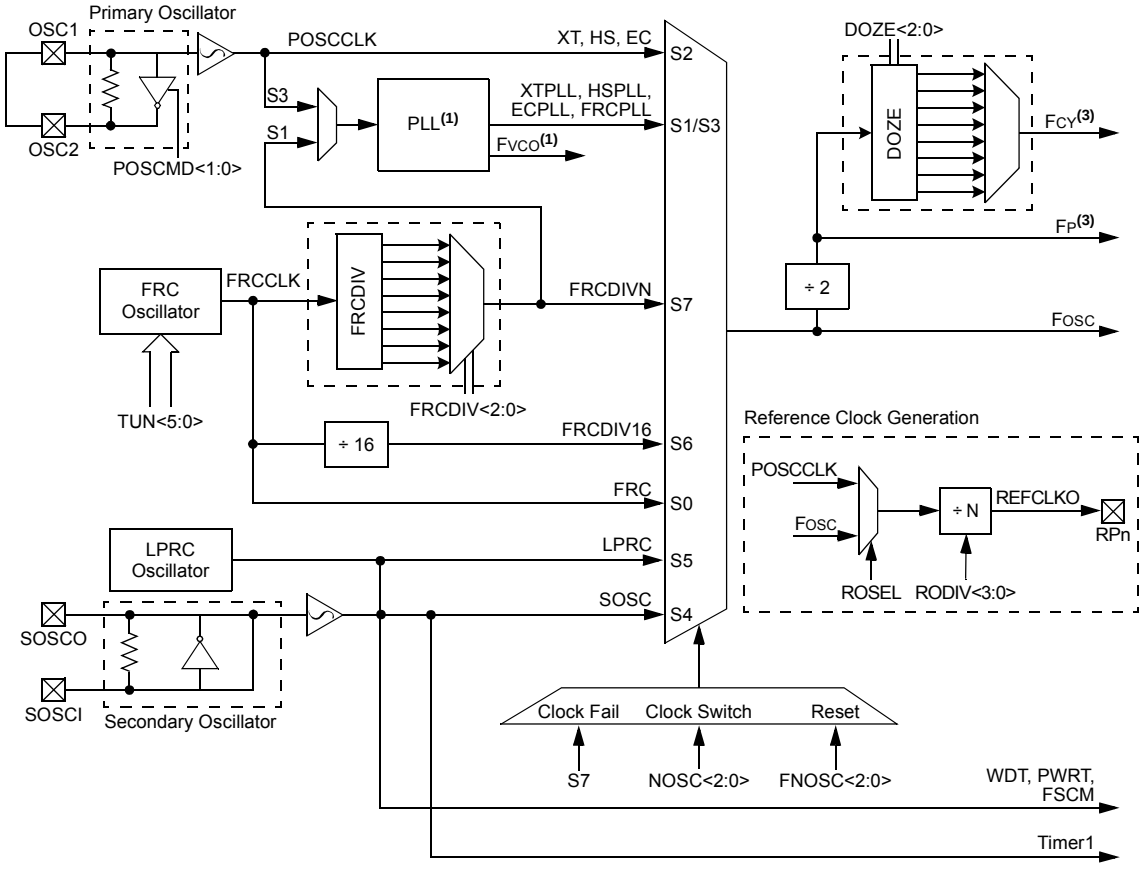
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGM3XX/6XX/7XX oscillator system provides:

- On-chip Phase-Locked Loop (PLL) to boost internal operating frequency on select internal and external oscillator sources
- On-the-fly clock switching between various clock sources
- Doze mode for system power savings
- Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Configuration bits for clock source selection

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL and FVCO details.

2: If the oscillator is used with XT or HS modes, an external parallel resistor with the value of 1 MΩ must be connected.

3: The term, FP, refers to the clock source for all peripherals, while FCY refers to the clock source for the CPU. Throughout this document, FCY and FP are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used with a doze ratio of 1:2 or lower.

10.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this cannot be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU Idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled, using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

A peripheral module is enabled only if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

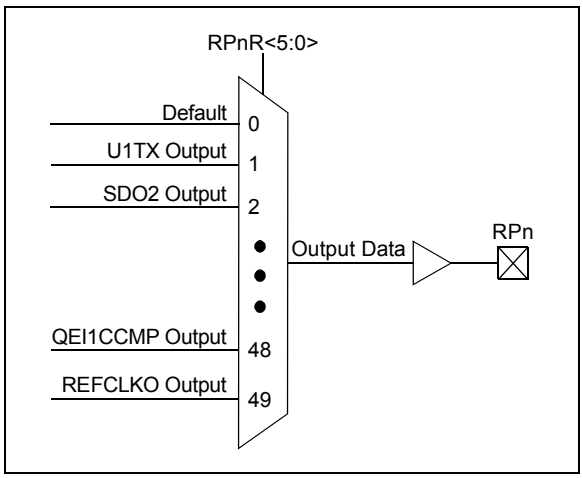
Note:	If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation).

11.4.5 OUTPUT MAPPING

In contrast to inputs, the outputs of the Peripheral Pin Select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPORx registers are used to control output mapping. Like the RPINRx registers, each register contains sets of 6-bit fields, with each set associated with one RPn pin (see Register 11-30 through Register 11-42). The value of the bit field corresponds to one of the peripherals and that peripheral's output is mapped to the pin (see Table 11-3 and Figure 11-3).

A null output is associated with the output register Reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 11-3: MULTIPLEXING REMAPPABLE OUTPUT FOR RPn



11.4.5.1 Mapping Limitations

The control schema of the peripheral select pins is not limited to a small range of fixed peripheral configurations. There are no mutual or hardware-enforced lockouts between any of the peripheral mapping SFRs. Literally any combination of peripheral mappings across any or all of the RPn pins is possible. This includes both many-to-one and one-to-many mappings of peripheral inputs and outputs to pins. While such mappings may be technically possible from a configuration point of view, they may not be supportable from an electrical point of view.

11.5 High-Voltage Detect

The dsPIC33EPXXXGM3XX/6XX/7XX devices contain High-Voltage Detection (HVD) which monitors the VCAP voltage. The HVD is used to monitor the VCAP supply voltage to ensure that an external connection does not raise the value above a safe level (~2.4V). If high core voltage is detected, all I/Os are disabled and put in a tri-state condition. The device remains in this I/O tri-state condition as long as the high-voltage condition is present.

11.6 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 33-10 under “Injection Current”, have internal protection diodes to VDD and VSS. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

Note:	Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUx and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to ~(VDD – 0.8), not VDD. This value is still above the minimum VIH of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specifications. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:

   VOH = 2.4V @ IOH = -8 mA and VDD = 3.3V

   The maximum output current sourced by any 8 mA I/O pin = 12 mA.

   LED source current < 12 mA is technically permitted. Refer to the VOH/IOH graphs in **Section 33.0 “Electrical Characteristics”** for additional information.

REGISTER 11-23: RPINR29: PERIPHERAL PIN SELECT INPUT REGISTER 29

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SCK3R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SDI3R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **SCK3R<6:0>:** Assign SPI3 Clock Input (SCK3) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **SDI3R<6:0>:** Assign SPI3 Data Input (SDI3) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 14-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	IC32(1)
bit 15							bit 8

R/W-0	R/W/HS-0	U-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-1
ICTRIG(2)	TRIGSTAT(3)	—	SYNCSEL4(4)	SYNCSEL3(4)	SYNCSEL2(4)	SYNCSEL1(4)	SYNCSEL0(4)
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8 **IC32:** Input Capture x 32-Bit Timer Mode Select bit (Cascade mode)(1)
- 1 = Odd ICx and Even ICx form a single 32-bit input capture module
- 0 = Cascade module operation is disabled

bit 7 **ICTRIG:** Input Capture x Trigger Operation Select bit(2)
- 1 = Input source is used to trigger the input capture timer (Trigger mode)
- 0 = Input source is used to synchronize the input capture timer to the timer of another module (Synchronization mode)

bit 6 **TRIGSTAT:** Timer Trigger Status bit(3)
- 1 = ICxTMR has been triggered and is running
- 0 = ICxTMR has not been triggered and is being held clear

bit 5 **Unimplemented:** Read as '0'

Note 1: The IC32 bit in both the Odd and Even ICx must be set to enable Cascade mode.

2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.

3: This bit is set by the selected input source (selected by SYNCSEL<4:0> bits); it can be read, set and cleared in software.

4: Do not use the ICx module as its own Sync or Trigger source.

5: This option should only be selected as a trigger source and not as a synchronization source.

6: Each Input Capture x module (ICx) has one PTG input source. See **Section 25.0 "Peripheral Trigger Generator (PTG) Module"** for more information.
PTGO8 = IC1, IC5
PTGO9 = IC2, IC6
PTGO10 = IC3, IC7
PTGO11 = IC4, IC8

REGISTER 14-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Input Source Select for Synchronization and Trigger Operation bits(4)

11111 = Capture timer is unsynchronized
11110 = Capture timer is unsynchronized
11101 = Capture timer is unsynchronized
11100 = CTMU trigger is the source for the capture timer synchronization
11011 = ADC1 interrupt is the source for the capture timer synchronization(5)
11010 = Analog Comparator 3 is the source for the capture timer synchronization(5)
11001 = Analog Comparator 2 is the source for the capture timer synchronization(5)
11000 = Analog Comparator 1 is the source for the capture timer synchronization(5)
10111 = Input Capture 8 interrupt is the source for the capture timer synchronization
10110 = Input Capture 7 interrupt is the source for the capture timer synchronization
10101 = Input Capture 6 interrupt is the source for the capture timer synchronization
10100 = Input Capture 5 interrupt is the source for the capture timer synchronization
10011 = Input Capture 4 interrupt is the source for the capture timer synchronization
10010 = Input Capture 3 interrupt is the source for the capture timer synchronization
10001 = Input Capture 2 interrupt is the source for the capture timer synchronization
10000 = Input Capture 1 interrupt is the source for the capture timer synchronization
01111 = GP Timer5 is the source for the capture timer synchronization
01110 = GP Timer4 is the source for the capture timer synchronization
01101 = GP Timer3 is the source for the capture timer synchronization
01100 = GP Timer2 is the source for the capture timer synchronization
01011 = GP Timer1 is the source for the capture timer synchronization
01010 = PTGx trigger is the source for the capture timer synchronization(6)
01001 = Capture timer is unsynchronized
01000 = Output Compare 8 is the source for the capture timer synchronization
00111 = Output Compare 7 is the source for the capture timer synchronization
00110 = Output Compare 6 is the source for the capture timer synchronization
00101 = Output Compare 5 is the source for the capture timer synchronization
00100 = Output Compare 4 is the source for the capture timer synchronization
00011 = Output Compare 3 is the source for the capture timer synchronization
00010 = Output Compare 2 is the source for the capture timer synchronization
00001 = Output Compare 1 is the source for the capture timer synchronization
00000 = Capture timer is unsynchronized

Note 1: The IC32 bit in both the Odd and Even ICx must be set to enable Cascade mode.

2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.

3: This bit is set by the selected input source (selected by SYNCSEL<4:0> bits); it can be read, set and cleared in software.

4: Do not use the ICx module as its own Sync or Trigger source.

5: This option should only be selected as a trigger source and not as a synchronization source.

6: Each Input Capture x module (ICx) has one PTG input source. See **Section 25.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO8 = IC1, IC5
PTGO9 = IC2, IC6
PTGO10 = IC3, IC7
PTGO11 = IC4, IC8

16.1.2 WRITE-PROTECTED REGISTERS

On dsPIC33EPXXXGM3XX/6XX/7XX devices, write protection is implemented for the IOCONx and FCLCONx registers. The write protection feature prevents any inadvertent writes to these registers. This protection feature can be controlled by the PWMLOCK Configuration bit (FOSCSEL<6>). The default state of the write protection feature is enabled (PWMLOCK = 1). The write protection feature can be disabled by configuring: PWMLOCK = 0.

To gain write access to these locked registers, the user application must write two consecutive values of 0xABCD and 0x4321 to the PWMKEY register to perform the unlock operation. The write access to the IOCONx or FCLCONx registers must be the next SFR access following the unlock process. There can be no other SFR accesses during the unlock process and subsequent write access. To write to both the IOCONx and FCLCONx registers requires two unlock operations.

The correct unlocking sequence is described in Example 16-1.

EXAMPLE 16-1: PWM1 WRITE-PROTECTED REGISTER UNLOCK SEQUENCE

```
; FLT32 pin must be pulled high externally in order to clear and disable the fault
; Writing to FCLCON1 register requires unlock sequence

mov  #0xabcd, w10          ; Load first unlock key to w10 register
mov  #0x4321, w11          ; Load second unlock key to w11 register
mov  #0x0000, w0           ; Load desired value of FCLCON1 register in w0
mov  w10, PWMKEY           ; Write first unlock key to PWMKEY register
mov  w11, PWMKEY           ; Write second unlock key to PWMKEY register
mov  w0, FCLCON1           ; Write desired value to FCLCON1 register

; Set PWM ownership and polarity using the IOCON1 register
; Writing to IOCON1 register requires unlock sequence

mov  #0xabcd, w10          ; Load first unlock key to w10 register
mov  #0x4321, w11          ; Load second unlock key to w11 register
mov  #0xF000, w0           ; Load desired value of IOCON1 register in w0
mov  w10, PWMKEY           ; Write first unlock key to PWMKEY register
mov  w11, PWMKEY           ; Write second unlock key to PWMKEY register
mov  w0, IOCON1            ; Write desired value to IOCON1 register
```

REGISTER 17-6: POSxHLD: POSITION COUNTER x HOLD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POSHLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POSHLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **POSHLD<15:0>:** Holding Register for Reading and Writing POSxCNT bits

REGISTER 17-7: VELxCNT: VELOCITY COUNTER x REGISTER

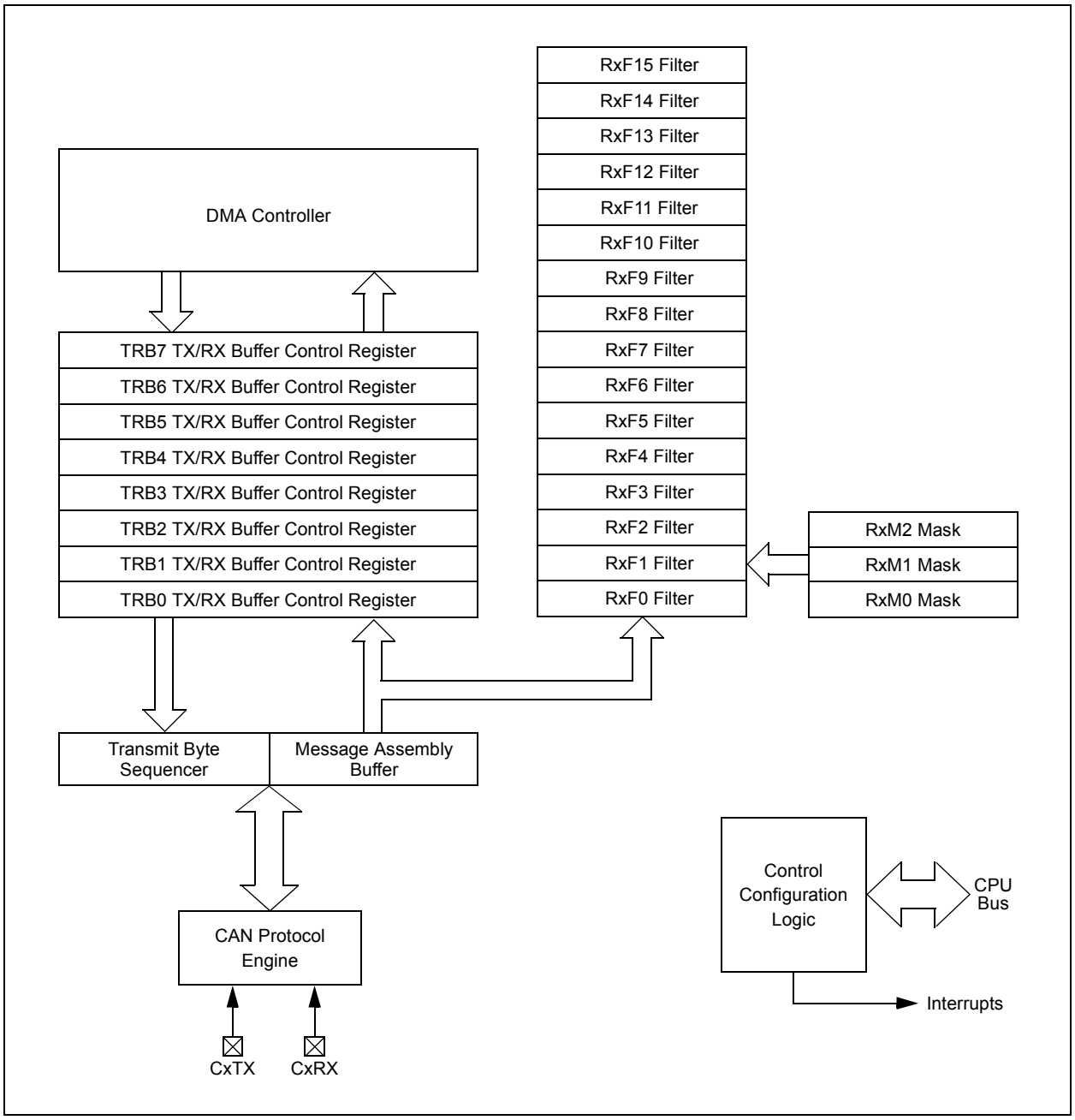
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
VELCNT<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
VELCNT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **VELCNT<15:0>:** Velocity Counter x bits

FIGURE 21-1: CANx MODULE BLOCK DIAGRAM



21.2 Modes of Operation

The CANx module can operate in one of several operation modes selected by the user. These modes include:

- Initialization mode
- Disable mode
- Normal Operation mode
- Listen Only mode
- Listen All Messages mode
- Loopback mode

Modes are requested by setting the REQOP<2:0> bits (CxCTRL1<10:8>). Entry into a mode is Acknowledged by monitoring the OPMODE<2:0> bits (CxCTRL1<7:5>). The module does not change the mode and the OPMODEx bits until a change in mode is acceptable, generally during bus Idle time, which is defined as at least 11 consecutive recessive bits.

28.1 PMP Control Registers

REGISTER 28-1: PMCON: PARALLEL MASTER PORT CONTROL REGISTER(3)

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PMPEN	—	PSIDL	ADRMUX1	ADRMUX0	PTBEEN	PTWREN	PTRDEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0(1)	R/W-0(1)	R/W-0(1)	R/W-0	R/W-0	R/W-0
CSF1	CSF0	ALP	CS2P	CS1P	BEP	WRSP	RDSP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at Reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PMPEN:** Parallel Master Port Enable bit
1 = PMP module is enabled
0 = PMP module is disabled, no off-chip access is performed

bit 14 **Unimplemented:** Read as '0'

bit 13 **PSIDL:** PMP Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-11 **ADRMUX<1:0>:** Address/Data Multiplexing Selection bits
11 = Reserved
10 = All 16 bits of address are multiplexed on PMD<7:0> pins
01 = Lower eight bits of address are multiplexed on PMD<7:0> pins, upper eight bits are on PMA<15:8>
00 = Address and data appear on separate pins

bit 10 **PTBEEN:** Byte Enable Port Enable bit (16-Bit Master mode)
1 = PMBE port is enabled
0 = PMBE port is disabled

bit 9 **PTWREN:** Write Enable Strobe Port Enable bit
1 = PMWR/PMENB port is enabled
0 = PMWR/PMENB port is disabled

bit 8 **PTRDEN:** Read/Write Strobe Port Enable bit
1 = PMRD/$\overline{\text{PMWR}}$ port is enabled
0 = PMRD/$\overline{\text{PMWR}}$ port is disabled

bit 7-6 **CSF<1:0>:** Chip Select Function bits
11 = Reserved
10 = PMCS1 and PMCS2 function as Chip Select
01 = PMCS2 functions as Chip Select, PMCS1 functions as Address Bit 14
00 = PMCS1 and PMCS2 function as Address Bits 15 and 14

bit 5 **ALP:** Address Latch Polarity bit(1)
1 = Active-high ($\overline{\text{PMALL}}$ and $\overline{\text{PMALH}}$)
0 = Active-low (PMALL and PMALH)

bit 4 **CS2P:** Chip Select 1 Polarity bit(1)
1 = Active-high ($\overline{\text{PMCS2}}$)
0 = Active-low (PMCS2)

Note 1: These bits have no effect when their corresponding pins are used as address lines.
2: PMCS1 applies to Master mode and PMCS applies to Slave mode.
3: This register is not available on 44-pin devices.

TABLE 33-39: SPI2 AND SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCKx Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 33-48: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(4)**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG +2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	**(Note 3)**

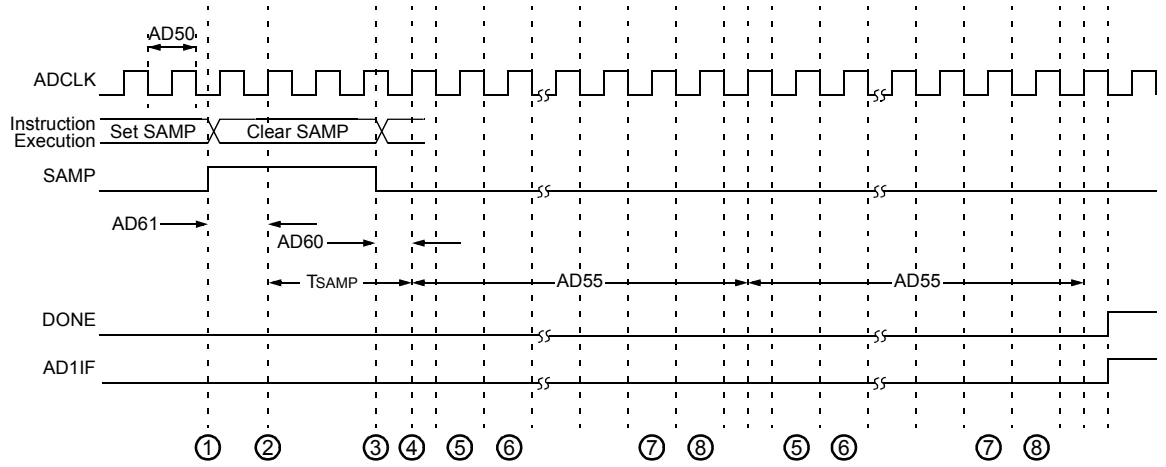
Note 1: BRG is the value of the I^2C Baud Rate Generator. Refer to the "*dsPIC33/PIC24 Family Reference Manual*", **"Inter-Integrated Circuit™ (I^2C™)"** (DS70000195). Please see the Microchip web site for the latest "*dsPIC33E/PIC24E Family Reference Manual*" sections.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

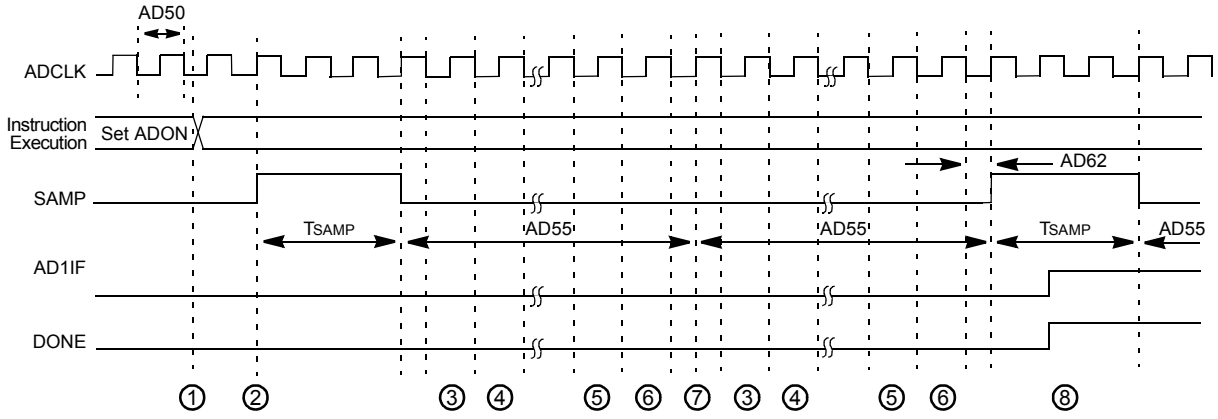
4: These parameters are characterized, but not tested in manufacturing.

FIGURE 33-39: ADC1 CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRCG = 0)



1. – Software sets AD1CON1. SAMP to start sampling.
2. – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) of the *"dsPIC33/PIC24 Family Reference Manual"*.
3. – Software clears AD1CON1. SAMP to start conversion.
4. – Sampling ends, conversion sequence starts.
5. – Convert bit 9.
6. – Convert bit 8.
7. – Convert bit 0.
8. – One TAD for end of conversion.

FIGURE 33-40: ADC1 CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRCG = 0, SAMC<4:0> = 00010)



1. – Software sets AD1CON1. ADON to start ADC operation.
2. – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) of the *"dsPIC33/PIC24 Family Reference Manual"*.
3. – Convert bit 9.
4. – Convert bit 8.
5. – Convert bit 0.
6. – One TAD for end of conversion.
7. – Begin conversion of next channel.
8. – Sample for time specified by SAMC<4:0>.

TABLE 34-8: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
HDO10	VOL	**Output Low Voltage** 4x Sink Driver Pins(2)	—	—	0.4	V	IOL ≤ 5 mA, VDD = 3.3V **(Note 1)**
		Output Low Voltage 8x Sink Driver Pins(3)	—	—	0.4	V	IOL ≤ 8 mA, VDD = 3.3V **(Note 1)**
HDO20	VOH	**Output High Voltage** 4x Source Driver Pins(2)	2.4	—	—	V	IOH ≥ -10 mA, VDD = 3.3V **(Note 1)**
		Output High Voltage 8x Source Driver Pins(3)	2.4	—	—	V	IOH ≥ 15 mA, VDD = 3.3V **(Note 1)**
HDO20A	VOH1	**Output High Voltage** 4x Source Driver Pins(2)	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V **(Note 1)**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V **(Note 1)**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V **(Note 1)**
		Output High Voltage 8x Source Driver Pins(3)	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V **(Note 1)**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V **(Note 1)**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V **(Note 1)**

Note 1: Parameters are characterized, but not tested.

2: Includes all I/O pins that are not 8x Sink Driver pins (see below).

3: Includes the following pins:
For 44-pin devices: RA3, RA4, RA7, RA9, RA10, RB7, RB<15:9>, RC1 and RC<9:3>
For 64-pin devices: RA4, RA7, RA<10:9>, RB7, RB<15:9>, RC1, RC<9:3>, RC15 and RG<8:7>
For 100-pin devices: RA4, RA7, RA9, RA10, RB7, RB<15:9>, RC1, RC<9:3>, RC15, RD<3:1> and RG<8:6>

TABLE 34-9: DC CHARACTERISTICS: PROGRAM MEMORY

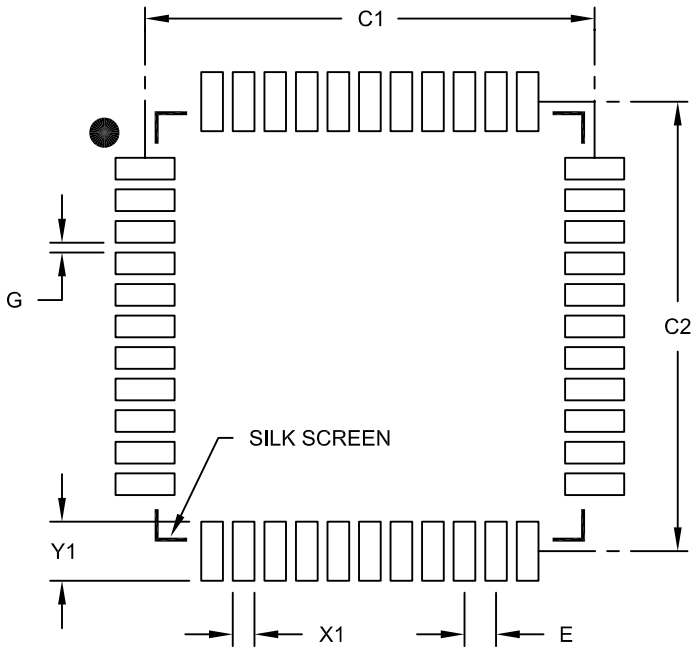
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
HD130	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +150°C(2)
HD134	TRETD	Characteristic Retention	20	—	—	Year	1000 E/W cycles or less and no other specifications are violated

Note 1: These parameters are assured by design, but are not characterized or tested in manufacturing.

2: Programming of the Flash memory is allowed up to +150°C.

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.80 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B